

# BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



## 647 SERIES

High-Performance Heat Sinks for Vertical Board Mounting

TO-220

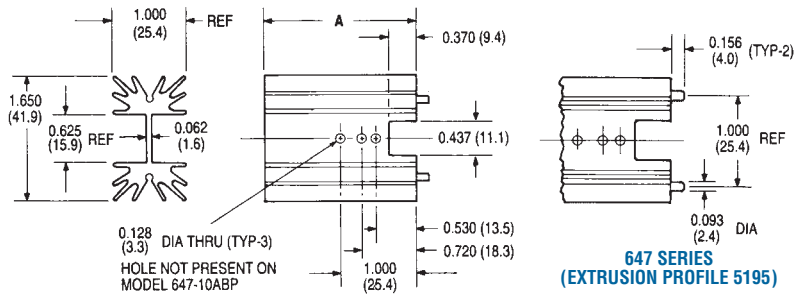
Standard P/N	Height Above PC Board "A" in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
647-10ABEP	1.000 (25.4)	1.650 (41.9) x 1.000 (25.4)	42°C @ 6W	3.8°C/W @ 200 LFM	0.055 (24.95)
647-15ABEP	1.500 (38.1)	1.650 (41.9) x 1.000 (25.4)	37°C @ 6W	3.5°C/W @ 200 LFM	0.075 (34.02)
647-175ABEP	1.750 (44.5)	1.650 (41.9) x 1.000 (25.4)	34°C @ 6W	3.3°C/W @ 200 LFM	0.090 (40.82)
647-20ABEP	2.000 (50.8)	1.650 (41.9) x 1.000 (25.4)	31°C @ 6W	3.1°C/W @ 200 LFM	0.104 (47.17)
647-25ABEP	2.500 (63.5)	1.650 (41.9) x 1.000 (25.4)	25°C @ 6W	2.8°C/W @ 200 LFM	0.125 (56.70)

Material: Aluminum, Black Anodized

Wave-solderable pins on 1 in. centers for vertical mounting of larger devices on printed circuit boards. Maximum semiconductor package width: 0.625 (15.9). Refer to the Accessory

Products section for thermal interface materials, 126 Series silicone-free thermal compounds, and other accessories products.

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS

